L Number	Hits	Search Text	DB	Time stamp
1	153	(438/$.ccls. and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131) and (semiconductor adj packag$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/11 10:10
3	3	(("6507102") or ("6395578") or ("5596231")).PN.	USPAT	2003/07/11 10:45
-	315	438/106 and cavity and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:05
-	287	(438/106 and cavity and via) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:29
-	2203	438/106.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:28
-	191	438/106.ccls. and cavity and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:13
-	166	(438/106.ccls. and cavity and via) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:14
-	666	438/$.ccls. and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:30
-	1605	257/$.ccls. and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:31
-	415	(257/$.ccls. and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131) and (semiconductor adj packag$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/01 12:32
-	537	(semiconductor adj packag$6) and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:07
-	1327	438/106.ccls. and (cavity or via or aperture or open$4 or trenches or holes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:07
-	537	(semiconductor adj packag$6) and cavity and via and (encapsula$6 or underfill$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:08
-	427	(438/106.ccls. and (cavity or via or aperture or open$4 or trenches or holes)) and (encapsula$6 or underfill$4) and @ad<=20020131	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/07 12:19